die 120 and 130 may be processors of the same or a different type than unpackaged die 110. Various embodiments of the present invention may employ different combinations of unpackaged semiconductor die 110 and packaged semiconductor die 120 and 130, including the use of two unpackaged semiconductor die 110 and only one packaged semiconductor die 120, or multiple packaged semiconductor die 120 and 130 with no unpackaged semiconductor die 110.

Please replace the paragraph beginning on page 4, line 6 with the following:

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FIG. 2 illustrates a partially completed multi-die module. Multi-die module substrate 140 is shown with unpackaged semiconductor die 110 attached in preparation for wire bonding. In one embodiment, multi-die module substrate 140 is a built up substrate having four to six layers. In another embodiment, multi-die module substrate 140 is a Bizmalemide Triazine (BT) substrate having two to six layers. It will be appreciated that any suitable substrate may be employed according to the teachings set forth herein.

Please replace the paragraph beginning on page 4, line 12 with the following:

FIG. 3 illustrates the partially completed multi-die module of FIG. 2, but now bond wires 175 have been added to make an electrical connection between multi-die module substrate 140 and unpackaged semiconductor die 110. In at least one embodiment, bond wires 175 are made of a corrosion resistant material, such as gold, to resist corrosion, but other suitable wire types or similar means of electrical connection may be employed as desired.

Please replace the paragraph beginning on page 6, line 1 with the following:

FIG. 8 illustrates another method of insulating electrical connections between unpackaged semiconductor die 111 and multi-die module substrate 140. Since all of the

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electrical connections are underneath unpackaged semiconductor die 111, there is no need for total encapsulation of unpackaged semiconductor die 111 to protect the electrical connections. Consequently, unpackaged semiconductor die 111 is underfilled with underfill material 170. Underfill material 170 may include, but is not limited to, ASEUA03 and ASEUA04 types of underfill materials.